

Index

A

a-Si solar cell/module 236
a-Si:C 236, 257, 314
a-Si:Ge 74, 236, 257, 314
a-Si:H 67, 73-74, 93-94, 136, 236, 239, 314
absorption coefficient 5, 11-13, 27, 51, 53, 57, 66-68, 75, 80, 84, 92, 97, 109, 140, 174
absorption depth 12-14, 28, 55, 66, 68, 140, 143, 163, 263
absorption peak 69
absorption spectra 13, 135-136, 145
AC coupled system 339
accelerated aging 292-293
accelerated depreciation 247
accelerated test methodology 260
acceptable quality limit (AQL) 293
activation energy 73, 271
Ag paste 175
aging characteristics 259
Al paste 175
Al-Si alloy 176
albedo 326
aluminium nitride
AM1.5 278, 323, 353
AM1.5G 118, 278-279
AM 0 1, 3-4
AM 1 1, 3-4, 10, 15, 26, 29, 45, 90, 99, 106-107, 113, 117, 127, 130, 156, 223-224
anatase 121
anisotropy 22-24
anodized aluminium
anthracene 134, 138, 156
Anti-Reflection Coating (ARC) 56-57, 172, 285
ARC on glass 211
Arrhenius relationship 271
aspect ratio 176, 179, 183
Atomic Layer Deposition (ALD) 88

B

back metal 161, 180, 198
back reflector 55-56, 163
back sheet 206-207, 212, 219, 238, 248, 250-251, 260-261, 265, 268-269, 271-272, 296-297, 300-305, 310-311, 314
Back Surface Field (BSF) 54, 61, 63, 112, 175
background ambient radiation 263
backtracking 385-387
Balance Of System (BOS) 358-359
band offset 22, 74, 78
bandgap narrowing 108
barrier height 9, 18-20, 28, 49-51, 63, 79
bath tub curve 288-290
battery
 backup time 336
 charging discharging efficiency 336
 energy storage capacity 377
 flooded 376, 380
 Lead Acid (Pb-acid) 371
 Li 10, 37, 95, 120, 371-372, 374, 376, 395
 Ni-Cd 371
 Valve Regulated Lead Acid (VRLA) 376
Beers-Lambert Law 13
bi-directional inverter 339
bi-directional meter 384
binning 180-182, 197
bio-mass 337
black silicon 56-57, 64-65
blocking diodes 382, 395
boiling water test 309
BOM (Bill of Materials) 247, 248
boost converter 359
Bosch process 56
Bridgman 38, 193
buck converter 359
Buck-Boost converter 359
buffer layers 90

bulk plasma frequency 58
 bulk plasmons
 Burgers vector of dislocation 104
 buried Contact 160, 183, 185-186, 188, 198
 bus bars 162
 continuous 39, 66, 92, 124, 150, 161, 187, 298,
 300, 304, 315, 341, 390
 segmented 161-162, 266
 bussing leads 217
 bypass Diode Thermal Test 296, 308, 313
 bypass diodes 194, 202, 204, 207, 209, 227-229,
 231, 234-235, 238, 255-257, 308, 382

C

C-V relation 17
 C60 137, 145
 Cadmium Telluride (CdTe) 203
 cap layer 193, 196, 198
 capacity in Ah 377, 379
 Capacity Utilization Factor (CUF) 389-390, 392
 carbon credit 384, 392
 carbon footprint 78
 carbothermic reduction 31
 Carnot cycle 5-6
 Carrier Density Imaging (CDI) 164, 201
 CdSe 45, 60, 63, 124, 127, 141, 150-151
 CdS/Cu₂S 7, 203
 CdTe 13-14, 22, 29, 42, 45-46, 63, 66, 72-73, 77-80,
 85, 89, 92-94, 97, 117, 122-123, 125, 130, 133,
 159, 203, 241-242, 255, 295, 314, 320, 327,
 333-335, 352-356, 385, 392-394
 cell coupons 211-213, 216, 218-219, 225
 cell manufacturing 160-161, 167-168, 172, 185, 191,
 194, 241, 260, 266, 285, 304, 320
 cell string 204-205, 207-208, 225, 229, 256, 261-
 262, 268, 271-272, 306, 314
 cell tester
 Spectra Nova 181
 Spire 181, 258, 280, 283, 318
 Cell to Module (CTM) conversion loss 210, 258
 cell tower 341-342
 cell-tester 212
 cells
 hot carrier 153
 hybrid 6, 74, 84, 95, 148, 150-151, 155, 157,
 337, 400
 Li-diffused 10
 monitor 279-280, 285, 309, 313, 329
 multi-crystalline 13, 31-32, 37, 49-51, 62, 158,
 161, 163, 167, 172, 202, 211
 multi-junction 110, 116, 131, 134, 159, 202
 PID resistant 310, 312

point contact 61-63, 65
 thin silicon 200
 central inverter 320-322, 329-330, 344-345, 352,
 368-369, 371, 395
 certification 308-310, 313
 chalcocite phase 27-28
 chalcopyrite structure 75, 81
 charge controller 320, 329, 342-343, 353, 358, 366,
 372, 375-376, 379, 396-397, 399
 Charge Coupled Device (CCD) camera 263
 charge-discharge cycle 373
 Chemical Vapour Deposition (CVD) 320
 circuit breakers/fuses 383
 class A 278-279, 284, 315
 class AAA 278, 284
 classification of SPV system 336, 353
 climatic chamber 300
 Closed Space Sublimation (CSS) 241
 cluster deposition
 CNPPV 138
 co-evaporation 76, 242-243, 255
 co-sputtering 242-243, 255
 CO₂ emission 1, 351-352
 columnar grains 27, 37, 39
 columnar growth 38
 combiner box 343-344, 358
 complex refractive index 11
 Concentrated Photo-Voltaic (CPV) 160
 concentration factor 60, 130
 concentration profile 169-170
 conditioning unit 320, 329, 358
 conduction/valence bands 163
 conduction band discontinuity 23
 conductive adhesive 211, 258
 conical surface structure 57
 connectors 358
 constant failure rate 290-291
 constant surface photovoltage technique 67
 constitutional super cooling 37
 controller circuit 363
 Copper Indium Diselenide (CIS) 241
 Copper Indium Gallium Diselenide (CIGS) 66, 90,
 203
 Copper Oxide 6
 Copper Phthalocyanine (CuPc) 142
 copper ribbon 261
 cosine law 323
 cost
 capital 6, 320, 346, 356
 manpower 247, 252-254, 393
 of depreciation 244
 of factory 244, 253

- of finance 243-244, 393
 - of input materials 243-244
 - of maintenance 252-253, 340
- counter-electrode 121-123, 126
- cover glass 204, 210-211, 213, 219-220, 225-227, 252, 255, 268, 307
- cracks
 - macro 163, 264
 - micro 61, 150, 160, 163, 237, 264-267, 269, 320-321, 329-330, 343, 345, 352, 368, 370-371, 393, 395-396
- crucible-less technique 36
- crucibles
 - graphite 34, 38-40, 122, 371
 - silicon nitride-coated graphite 38
 - quartz 38, 63, 87, 122
- crystal growth 32, 34-37, 64, 135, 161, 203, 241
- crystal structure 81, 83, 88
- crystalline Silicon (c-Si)
 - mono- or multi 158, 163
- crystallinity 84, 88, 125, 193
- CSP (Concentrated Solar Power) 326
- $\text{CuIn}_x\text{Ga}(1-x)\text{Se}_2$
- Cumulative Distribution Function (CDF) 290
- current
 - charging 128, 329, 336, 358, 371-377, 379-380, 382, 395-397
 - discharging 329, 336, 358, 371-374, 377, 379-380, 395, 397
 - photo-generated 52-53, 61, 90, 109, 161, 163, 165, 176, 182-183, 185, 215, 236, 241
 - saturation 7, 14, 43, 108-110, 215
 - short-circuit 7, 15, 45, 51, 53-56, 60, 63, 140
- cylindrical ingot 161
- Czochralski (CZ) growth 32, 34, 63, 161, 201
- D**
- Damp Heat (DH) 297, 300
- dangling bonds 48-51, 68, 71, 172, 174, 183, 193, 236, 240-241, 255
- DC pump 340
- DC-DC converter 358-360, 362-363, 365-366, 370, 396, 399
- deep level states 46
- de-lamination 233, 296-297
- decomposition potentials 123
- defect quality criteria 181
- defects
 - physical 56, 68, 82, 131, 134, 142, 150, 157, 163, 178, 186, 202, 233, 289, 334
 - visual 180, 197, 260-261, 266, 295-298, 300, 304, 315-316
- degassing 376, 380
- density function 290
- density of dangling bonds 68, 174, 236
- density of states 67-68
- depletion region 19-20, 53, 63
- deposition rate 72-73, 87, 94, 224
- Depth Of Discharge (DOD) 336, 372
- detailed balance limit 25, 30
- dichroic mirrors 106
- die casting 161
- dimethylformamide 86
- Diesel Generator (DG) 337, 346
- diffused light 167
- diffusion
 - coefficients 8, 11-12, 14, 35-37, 42, 44-45, 66, 135, 221, 280, 326, 334
 - constant source 170-171, 315
 - furnace 34, 38-39, 88, 168, 170
 - impurity 8, 31, 33-37, 40-41, 46-47, 51, 62-63, 148, 154-155, 168-169
 - limited source 169
 - phosphorus 120, 168, 241
- digenite 28
- diodes inside the laminates 229
- dipole layer 23
- Direct Normal Incident (DNI) 278, 323
- directional solidification 32, 36-39, 41, 62
- directionally selective filter 60
- dislocation 33-35, 39-40, 104
- dislocation density 35, 39
- distribution coefficients in GaAs 35
- distribution coefficients in Si 35
- djurleite 28
- doctor blading 134
- donors and acceptors 43, 144
- donor-(Aacceptor) (DA) interface 141
- double Junction 193
- double layer ARC 168, 172
- Double Printing (DP) 176
- double-exciton generation 152
- dry insulation test 268-272
- dual-source vapour deposition 86
- duty cycle 360-364, 396
- economic viability 220, 243, 255, 346, 353
- E**
- EDAX 88
- Edge-defined Film-Fed Growth (EFG) 40
- edge instability 40
- edge isolation 162, 171, 180, 187, 198, 266
- effective life time 165, 199
- effective mass 20, 58, 137

effective medium theory 56
 effective Richardson constant 20, 23
 efficiency
 CEC 366-367, 395-397
 coulomb 152, 379-380, 395, 397
 Euro 366-368, 395-397
 efficiency of the battery 379, 397
 efficiency of the converter 363
 Einstein relation 42
 Electro Luminance (EL) 180
 electrochemical deposition 75, 82
 electron affinity 18, 22-23, 79, 142
 Electron Blocking Layer (EBL) 144
 Electron Conducting Layer (ECL) 85
 electron-hole generation rate 51
 Electron-Reflector (ER) layer 79
 Electron Spin Resonance (ESR) signal 50, 71
 electronic load 279, 282, 313
 electroplating 175, 186, 202
 ellipsometry 173-174, 202
 emitted radiation 263, 326
 Emitter Wrap Through (EWT) 160, 188
 encapsulation 142, 211, 238, 258, 296, 318
 energy-band (E-k) diagram
 energy
 conservation 12, 67
 credits 383
 security 320
 energy density 3, 106, 371-372
 energy gap parameters
 energy loss details 386
 energy storage technologies 3, 371
 environment chamber 297
 epitaxial layers 100, 104, 113, 130, 160, 193
 epitaxial technique 160, 192
 epitaxy 66, 68, 97, 99-102, 130-131, 160
 ESR 50-51, 71
 etching
 an-isotropic 165
 electrochemical 56, 75, 82, 121-122, 124-125,
 128-130, 132, 318
 kinetics 167
 rates 37, 84, 101, 130, 165, 167, 295, 298, 379,
 394
 reactive ion 56, 64
 Ethyl Vinyl Acetate (EVA) 172, 205, 260, 268
 evaporation
 e-beam 113, 196-198
 thermal 5-6, 34-35, 40, 56, 82, 88, 105-106,
 108, 132, 151, 154, 196, 258, 264, 267, 296,
 298-299, 308, 313, 330, 337, 351-352, 392
 exciton binding energy 84, 90, 93, 136, 152, 155

exciton bottleneck 142
 exponential distribution 290-291
 extended reliability test 309
 External Quantum Efficiency (EQE) 91, 160, 221
 external soiling 220

F

femtosecond laser 57
 Fermi level 49-50, 108, 127, 140
 ferroelectric BaTiO₃ 84
 Fill Factor (FF) 7, 106, 140, 216, 277, 326
 fission 3, 148-149, 152
 fixed system 322-325, 327, 335, 352, 358, 385
 floating ground 311
 Float-zone (FZ) grown 61
 Float-zone (FZ) silicon 36
 fluidized bed-reactor 32
 fluorescent concentrators 55
 Fluorine-doped Tin Oxide (FTO) 85
 flywheel 371
 force gauge 262, 273
 formadinium iodide 84
 four probe method
 Fourier Transform Infra-Red (FTIR) spectroscopy
 174
 fractional distillation 32
 framing machine 206
 freezing temperature 376
 Frenkel excitons 135
 Fresnel lens 105
 Fresnel reflection 56
 Fresnel relation 11
 front gratings 55
 fullerene 137, 141, 145, 149-150, 152, 155

G

GaAs 12-14, 20, 22, 30, 35, 37, 41-47, 49-50, 62, 66,
 89, 92, 97-100, 102, 104, 108-110, 112-114,
 116-120, 124-125, 130-132, 151, 160, 192-
 193, 195-196, 198, 204, 240-241, 314
 GaInAs 113, 132, 241
 GaInAsP 132, 241
 galena (PbS)
 gallium nitride 101, 159, 203, 241
 galvanized aluminum frames 206
 gas jet deposition 73
 Gaussian distribution 182
 gel and peel strength 260
 geothermal energy 3
 germanium 8, 31, 64, 100, 151, 159-160, 192, 239
 glass hardness test 260

glass-on-glass module 238, 241
global temperature rise 2
global Warming 1, 28
grain boundary 49-50, 64, 137
grain boundary scattering 137
grain size 37, 50-51, 62, 73, 76, 87-88
granular polysilicon 33
Grätzel cells 125-127
greenhouse effect 326
green house gases 128
grid coverage loss 24
grid fingers 196
grid Parity 392-394, 396
grid spacing 113
grid-connected 5, 400
grounding strategy 311

H

hail test 296, 307-308, 313, 317
halide migration 89, 93
hazard rate 289-292
heat exchanger method 38
heliostat 6
hetero-interface 137
heterojunction
 broken gap 22
 planar 34, 39, 85, 88, 95, 132, 144, 155-157
 staggered 22
 straddled 22
Heterojunction with Intrinsic Thin Layer (HIT) 203
high pot tester 268-269
high power devices 36
high resolution microscopy 178
High Voltage Stress (HVS) 310
HIT cell
 single sided 118
 double sided 118
HOMO 135, 137, 139-140, 142, 147, 151, 155-156
homojunctions 14
hopping transport 137
hot spot 228, 231, 233, 275-277, 296-297, 308, 310, 313
Hubble Space Telescope 118
Humidity Freeze (HF) 297, 303
hybrid systems 337
hydro electricity 3, 392
hydrogen generation 128, 131
hydrogen peroxide (H₂O₂) 265, 300
hydrogen reduction 32
hydrogenated silicon nitride 172
hysteresis 84, 88, 92-93

I

i (intrinsic) layer 236
I-V characteristics 16, 20, 29, 45, 89, 125, 181, 196, 231-232, 234-235, 256, 277, 287, 328-332, 354, 363, 369-370, 396
ice gun 307
ideal diode equation 17
ideal PV cell 229
ideality factor n 215
image sensors 56
import-export energy meters 384
impurity segregation 51
in-situ characterization 259
inclination angle 322-323, 325
indirect band gap 14, 46, 55, 163, 263
indium nitride
Indium Phosphide (InP) 13, 22, 66,
Indium Zinc Oxide (IZO) 71
infant mortality 288, 293-295, 313, 315
Infra Red (IR) heating 175
infrared imaging 275
infra-red (IR) region 57
ingot casting 38, 62
ingot diameter 35
inkjet printing 134, 155, 175, 202
InP 13, 22, 45-46, 49, 66, 97, 100, 102, 104, 119-120, 124-125, 132, 151-152, 157, 204
insolation 1, 4-6, 15, 28-29, 53-54, 93, 104, 130, 320, 322-323, 345, 358, 385-386, 398
installed capacity 63, 248, 320, 330, 334, 338, 343, 353, 359, 366, 385, 387, 389-390, 396
Insulated Gate Bipolar Transistor (IGBT) 359
Insulated Gate Field Effect Transistor (IGFET) 359
integrated circuits (IC)s 33, 289
integrating sphere 167-168, 173, 201
inter-diffusion 135
Inter-digitated Back Contact (IBC) 160, 190
interconnection 117, 174, 194, 257-258
interfacial adhesion 135
interfacial modification 85, 95
intermolecular coupling 137
Internal Quantum Efficiency (IQE) 160, 221
internal resistance of the battery 372
Internal Spectral Response (ISR) 223
International Electrotechnical Commission (IEC) 295, 307
international space station 118-119
intrinsic carrier concentrations 43
intrinsic gettering 119
Inverse Photoemission Spectroscopy (IPES) 90
inversion layer 20

406 • Index

inverter
 central 320-322, 329-330, 343-346, 352, 368-371, 387-388, 393, 395
 micro 61, 150, 160, 163, 237, 264-267, 269, 320-321, 329-330, 343, 345, 352, 368, 370-371, 393, 395-396
 string 204-205, 207-208, 225, 228-229, 235-236, 255-256, 259, 261-262, 268, 271-272, 306, 310-311, 314, 320-321, 329-334, 343-345, 352-355, 358-359, 362, 365, 368-369, 371, 382-383, 387, 393, 395-396, 400
 inverter efficiency 336, 366, 379, 395
 ion exchange mechanism 27
 ion implantations 191
 irradiance pattern 345
 islanding 383-384
 isolation transformer 368-369, 395
 isotype 22
 ITO-coated glass 71, 73

J

junction box 207, 248
 4-way 208, 234, 247
 6-way 208
 junction depth 99, 108, 130, 168-171, 180
 junction temperature 308

K

k-conservation rule 67
 kerf losses 66
 kesterite 80-81, 95

L

lambertian back reflector 55-56
 lamination loss/gain 211
 lamination process 210, 255, 260-261, 269
 laser drilled holes 187
 laser micromachining 175
 laser scribing 40, 236, 241-242, 255
 laser source 263
 laser surface treatment 56
 lattice matching 99, 103, 113, 241
 lattice parameter 97
 lattice vibration 12
 lattice-matched systems 23
 layer-type compounds 124
 layup 205-206, 240, 255, 271
 leaky JB 269
 (LED) street lights 343, 347, 348
 Levelized Cost of Energy (LCOE) 392
 Levelized Energy Cost (LEC) 392

LID 207, 285, 334-335, 386
 lift-off photolithography 196, 198
 life-time killers 40
 lifetime
 bulk 13-14, 19, 48, 57-58, 63, 76, 89-90, 92, 121, 144-145, 148-149, 151-153, 155-158, 160, 164-165, 170, 172, 176, 183, 185, 189-190, 193, 198-199
 effective 20, 23, 40, 48-49, 56, 58, 63, 137, 144, 152, 165, 177, 184-185, 187-189, 199, 210, 214, 216-217, 220, 236, 250, 300, 339, 346, 356, 366, 379
 minority carrier 9, 14, 27, 36, 44, 52, 54, 61, 71, 73, 79, 98-99, 108, 119-122, 125, 129, 163-165
 surface 1, 4-5, 10-11, 19-20, 23, 27-28, 31, 40, 48-49, 51-59, 61, 63-65, 67, 74-75, 79, 84, 87-89, 99, 102, 104, 106, 112-114, 119, 122, 125-126, 129, 133, 144-145, 161, 163-172, 174-177, 183-185, 187-191, 193-194, 197-199, 201, 213, 220, 265, 278, 317, 322-323, 326, 353
 light capture by reflection 211
 Light Induced Degradation (LID) 285, 334, 386
 light pulse characteristics 280
 light source 167, 181, 278-280, 282-284, 313
 light trapping 56, 60, 64, 107, 150, 163, 166, 176, 199, 201, 258
 light-emitting devices 51
 Light-Induced Plating (LIP) 186
 lithium-doped silicon cells 132
 liquid phase epitaxy 99
 liquid-solid interface 38
 lithography 31, 160, 191, 194-197
 load profile 335-336, 348, 353, 355, 380
 localized surface plasma frequency 58
 localized heating 185, 231, 275, 313
 Long Range Order (LRO) 66
 long term durability 261, 262
 long-term stability 84, 125, 129-130, 135, 310
 longevity of the module 276
 LT panel 358
 luminescence 51, 60, 261, 263-264, 267-268
 Luminescent Solar Concentrators (LSC) 60
 LUMO 135, 137, 139-140, 142, 147, 151, 155-156

M

manufacturing-induced defects 264
 masks 191, 193, 200
 matching current density 91
 material fatigue 288
 Maximum Depth Of Discharge (MDOD) 372

- Maximum power point (MPP) 233
 Maximum Power Point Tracking (MPPT) 329, 358, 363
 MPPT based charge controller 342
 Mean Time to Failure (MTTF) 289
 mechanical and thermal stresses 264
 mechanical load test 296, 306, 313
 mechanical strength 55, 322
 MEH-PPV 138
 melting point 31, 34-35
 Micro Electro Mechanical Sensor (MEMS) 160
 meniscus 40
 mesa lithography/etch process 194, 195
 mesh 175
 mesoporous TiO₂ layer 86
 metal contacts 20, 90, 92, 161, 188, 191, 198
 metal coverage 176-178, 182-184, 187, 191
 metal fingers 21, 161, 182-183, 185-186, 199, 297, 300
 metal impurities 33, 48, 63, 163
 Metal-Intrinsic-N-P (MINP) structure 61
 metal paste 175-177, 186, 198, 300, 304
 Metal Wrap Through (MWT) 160, 187
 Metal-Insulator-Semiconductor (MIS) 14
 metal-semiconductor junctions 14
 Metallization 174-178, 186, 189, 191, 193, 196, 198-199
 Metalorganic Vapour Phase Epitaxy (MOVPE) 66, 100
 metallurgical grade Si 31
 Meteororm 345, 386
 Methyl Ammonium Tri-iodide (CH₃NH₃PbI₃) 84
 micro-grooved surface 61
 micromorph
 tandem silicon cell 73
 MIL-STD 883 289
 misfit strain 104
 mismatch between cells 211, 275
 mixed halide perovskites 87
 mobility
 drift 8-9, 19-20, 53, 67, 70, 140, 142
 field-effect 73
 Hall 30, 64, 67, 202, 318, 399
 module level efficiency 334
 module technology 204, 333, 385
 modules
 AC 104-106, 324, 328-330, 336, 338-343, 348-349, 353, 355, 358, 365, 369-370, 375, 379, 387-388, 395, 397
 degradation 47-48, 71-73, 83-85, 89-90, 92, 94, 120, 203, 233, 259-260, 262, 285, 288, 295-297, 304, 306-308, 310, 313, 317-319, 334, 346, 352, 359, 365, 374, 386, 390, 393-394, 398
 Molecular Beam Epitaxy (MBE) 66, 97
 momentum conservation 12
 mono- and multi-crystalline 167, 211
 monochromatic light 167
 monolithic III-V diode 194
 morphology 84, 86-87, 135
 MOS devices 48
 MPPT controller 363-366, 370, 395-396
 multi target 196
 Multi-channel acquisition 282
 multi-crystalline Si 13, 32, 161, 163, 167, 172
 Multi-Exciton Generation (MEG) 151, 155
 multi-junction 110, 116, 131, 134, 159, 202
 multiple epitaxial layers 193
 multiple passes 55
 multiple reflection 57
 multiple wire slicing 39
- N**
- nano-particle based synthesis 82
 nanocluster 145
 nanocrystalline Si 73
 nanocrystals 55, 65, 141, 148, 150-152, 155, 157
 nanoparticles 58-59, 86, 90, 126, 157
 nanostructures 55
 nanotechnology 65, 95, 150
 NASA 345, 386
 near-field coupling 59
 negative grounding 311
 net metering 337, 383-384, 395, 397-398, 400
 nitride family 116
 non-linear degradation rates 394
 nonagons 40
 normal hydrogen electrode 124
 Normal Operating Cell Temperature (NOCT) 282
 nuclear energy 3
- O**
- off-grid/grid interactive SPV systems 334
 ohmic contact 71, 76, 100, 112, 142, 196
 OLED 134
 on-grid systems 336, 358
 one sun 89, 107, 164
 one-diode model 215
 one-step precursor solution deposition 86
 opacity of the glass 220
 optical
 absorption depth 12-14, 28, 55, 66, 68, 140, 143, 163, 263

- absorption edge 51, 67, 108
- confinement 56, 64, 144, 151-152, 163, 166, 176, 199
- filters 55, 106-107, 167, 278
- path length 55-56, 60, 63, 144
- transmission 11, 20, 56, 90, 221, 392-393
- optimum tilt angle 385, 387
- organic 83-84, 87-88, 95, 134-143, 145-153, 155-157, 159-160, 175, 200, 297, 304
- organic-inorganic composites 141
- organic-organic composites 141
- Original Equipment Manufacturer (OEM) 279
- outdoor measurement 226, 284
- overall reflection 211
- overheating 371
- oxide etch 169-170
- P**
- p-i-n junction 236, 239
- p-n junction 7, 9, 14-21, 25-26, 30-31, 43, 45, 51, 54, 63, 68, 70, 98-99, 109, 112, 114, 118-121, 130, 161, 192, 194, 204, 233, 241, 243, 263-264, 298, 320
- P-V curves 216, 286
- PAN file 386
- parabolic collectors 5
- partially shaded cells 229
- Passivated Emitter and Rear Contact (PERC) 160
- Passivated Emitter Rear Locally diffused (PERL) 160
- Passivated Emitter Rear Totally diffused (PERT) 160
- passivation
 - back surface 54, 56, 61, 63-64, 112, 161, 166, 170, 175-176, 189, 197
 - hydrogen 32-33, 51, 101, 124, 128, 131, 133, 137, 172, 183, 198, 201, 236, 255, 265, 300
- payback period 203, 244-246, 248, 257, 314, 346, 352, 356
- PbS 5, 88, 148-149, 151, 157
- PC1D 223, 258
- PCPDTBT:PCBM 147
- PCU 320-322, 328, 330, 335-339, 349, 353, 358, 365-366, 382, 384
- peak efficiency of the inverter 366
- peak generation of power 372
- peak load 349, 359, 366, 379, 385, 395
- peak requirement of power 372
- peak sun hour 336, 345, 351, 359, 375, 397
- PECVD silicon nitride deposition 173
- PEDOT 138, 145, 147
- pentacene 136, 138, 148-149, 152-153, 155
- performance degradation 90, 233
- Performance Ratio (PR) 359
- perovskite nanowires 90
- perturbation and adjust 364
- perylene 142
- phase change 221
- phase diagram 28
- phase separation of Ag and Pb 176
- phase transition 84
- phenyl C61 butyric acid methyl ester 85
- phonon absorption 12-13
- phonon emission 12-13
- phosphine 101-102, 130
- Phospho-Silicate Glass (PSG) 169
- photo-corrosion 125
- Photoconductive Decay (PCD) 164
- photocurrent 4, 20, 53, 121, 139, 152-153, 172
- photoelectric effect 7
- photolithography 21, 113, 160, 175, 191, 193, 195-196, 198, 200
- photoluminescence 88, 151, 164, 201, 263
- Photovoltaic Effect 30, 121, 131
- Photovoltaic Geographical Information System (PVGIS) 386
- phthalocyanine (Pc) 138
- Planck distribution 25
- Planck's constant 7, 223
- plasma 55-56, 58, 63, 66, 68, 71, 73, 97, 172-173, 201-203
- plasma deposition 55, 68, 97
- Plasma Enhanced Chemical Vapour Deposition (PECVD) 203
- plasmon excitation 55
- plasmon resonance 58-59
- Poisson's ratio 104
- polarization 174, 221, 310
- polaron formation 137, 150
- polyacetylene 138, 155
- polycrystalline 39, 50-51, 64, 66, 94, 97, 121, 127, 133
- polydiacetylene 138
- polydispersity 148
- Polymethylmethacrylate (PMMA) 60
- polypyrrole 127
- polysilicon slim rod 32
- Potential Induced Degradation (PID) 288, 310, 359
- power
 - converter 353, 358-360, 362-366, 370, 395-396, 399
 - dissipation 231-232, 385
- Power Management Unit (PMU) 341
- PPV 138

Pressure Cooker Test (PCT) 309
 Printed Circuit Board (PCB) 175
 printing 37, 78-79, 82, 94, 134-135, 155, 175-176,
 179, 183-185, 187-188, 196, 198-199, 202
 Probability Distribution Function (PDF) 290
 probe heads 181
 profit margin 243, 333
 profitability 216, 247
 project viability 394
 pseudo-direct gap 66
 pseudomorphic layer 103
 pull strength 261-263
 Pulse Width Modulation (PWM) 360
 pulsed simulator 280
 pumped-hydro 371
 pumps 321
 purification 31-33, 36-37, 39-40
 PV Design Pro 345
 PVSOL 345
 PVSyst 345, 359, 386-391, 395, 400
 pyramid-like structure 165
 PVWATTS 345, 400
 pyrolysis of silane 32
 pyrometer 34, 269

Q

qualification 289, 292-296, 308-309
 qualification test plan 308
 quality and reliability standards 260, 292
 Quality Assurance (QA) 252
 Quality Control (QC) 252, 260
 quality level 260
 quantum dots 60, 151, 157
 quantum efficiency 91, 109, 140, 152-153, 157, 160,
 200, 220-221, 223
 quartz-lined graphite crucible 34
 quasi-direct gap 13, 92
 Quasi-Steady State Photoconductance (QSS-PC) 164
 quaternary 80-81, 95, 97, 160

R

r.f. glow discharge deposition 68
 r.f. induction furnace 34
 Radial Distribution Function (RDF) 67
 radiation
 damage 10, 57, 119-120, 130, 132, 143-144,
 165, 186-187, 193-194, 196, 198, 204, 228,
 231, 233, 295-298, 307
 detectors 36
 diffuse 5, 9, 19, 54-56, 64, 104, 142, 154, 168-

169, 172, 233
 direct 5, 7, 11-14, 22, 27-28, 42, 46, 66, 68,
 80, 84, 89, 92, 97-100, 109, 121-122, 129-130,
 133, 170, 176, 181, 204, 217, 241, 252-254,
 278, 323, 341
 flux 3-4, 9, 51, 109, 111, 116, 167, 261
 immunity 192
 reflected 1, 5, 11, 55-56, 118, 154, 167, 172,
 174, 176, 199, 220-221, 245, 326
 UV 1, 58, 127, 150, 259, 296-298, 310, 313
 radioactive waste 3
 randomly textured surfaces 55
 re-certification 308
 rectifying contact 19
 rear gratings 55
 recombination
 centre 1, 84, 386
 direct 5, 7, 11-14, 22, 27-28, 42, 46, 66, 68,
 80, 84, 89, 92, 97-100, 109, 121-122, 129-130,
 133, 170, 176, 181, 204, 217, 241, 252-254,
 278, 323, 341
 mechanisms 25, 47, 65, 151, 156, 164, 204,
 288
 non-radiative 84, 89-90, 154, 263
 radiative 25-26, 84, 89-90, 154, 263-264, 314
 trap-assisted 148
 redox 121-124, 126-127, 129, 142
 redox systems 123
 reference module
 daily 28, 285, 385, 390, 395
 original (primary) 285
 secondary 89, 171, 285, 311, 346, 371
 reflection coefficient 11, 51, 140, 168
 reflection from the ground and surroundings 323
 reflection loss 24, 165-166, 172-173, 183, 193, 198-
 199, 220, 222, 388
 reflectivity 167, 222-223
 refractive index 11, 56, 60, 172-174, 191, 197, 220,
 222, 224-225
 relative abundance 78, 80
 relative humidity 268, 300, 304, 310
 reliability
 function 18-19, 26, 51, 53, 67, 73, 109, 112-
 113, 141-142, 144, 156, 167, 220-221, 223-
 224, 253, 263, 269, 273, 289-292, 329-330,
 366, 370, 378, 386, 396
 issues 64, 188, 229, 243, 259, 264, 310, 313,
 318, 325, 359, 372, 390, 399
 modeling 94, 178, 258
 standards 118, 243, 259-260, 263, 278, 288-
 289, 292, 295-296, 306-307, 310, 313, 366

410 • Index

- standards and protocols 259, 288
 - tests 260, 268-269, 284-285, 295, 297, 304, 308-309, 313-314
 - Reliability Monitoring Programme (RMP) 309
 - renewable energy
 - initiatives 320
 - resistance
 - contact 21, 24, 27, 61-63, 65, 71-72, 74, 76, 79, 90, 100, 107-108, 112, 120-121, 126, 139, 142-143, 145, 148, 160-161, 174-176, 183, 185-191, 193, 196-198, 201-202, 216-217, 231, 239, 262-263, 273, 300
 - lumped 216-217
 - ribbon's 217
 - series 6-7, 16-17, 21, 24, 28-30, 94, 106, 108-110, 117, 144-145, 158, 179, 185, 191, 194, 197, 201, 204, 210-211, 213, 215-219, 222, 225, 227, 229, 237, 239-240, 255, 258, 261, 271, 282, 310, 330-333, 358, 369-370, 377, 380, 386, 396
 - shunt 16-17, 24, 28-29, 180, 215, 229, 231, 234, 256, 266, 282, 298
 - spreading 171, 386
 - wiring 336, 345, 363, 389, 393
 - resistivity
 - bus bar 161-162, 175-177, 182, 184, 199, 211-217, 219, 256, 261-263, 266, 296
 - gradient 6, 8, 33, 37-38, 176
 - map 10, 89, 171
 - solder 216, 219, 261, 296
 - resonant tunneling devices 153
 - return of investment 394
 - RF electric field 173
 - ribbon silicon 39, 158
 - Richardson constant 20, 23
 - roll-to-roll production 69
 - Room Temperature Vulcanization (RTV) 273
 - rutile 121
- S**
- saw damage 165, 187, 198
 - Scanning Electron Microscope (SEM) 90, 165
 - Schottky barriers 14, 19-20, 49
 - screen (mask) 175
 - screen printing 37, 78-79, 82, 175, 196
 - Secondary Ion Mass Spectroscopy (SIMS) 171
 - selective electroplating 186
 - selective emitter 160, 183, 185-186, 189-190, 198, 200-201
 - self-trapping 137
 - selling price 243, 250
 - semiconductor-grade silicon 33
 - semiconductor devices 30, 64, 119, 131, 289, 291, 293-294
 - semiconductor surfaces 48
 - semiconductors
 - amorphous 13, 46, 66-68, 92-94, 97, 117, 137, 159-160, 203, 238, 320, 325
 - direct gap 12-14, 66, 68, 84, 92, 99-100
 - indirect gap 11-12, 14, 99, 204
 - ternary 75, 81, 160
 - shaded cell 194, 227-235, 275, 296
 - shading loss 178, 183, 186, 188, 198
 - shadowing of cells 227
 - shear modulus 104
 - sherescan 171
 - Shockley-Queisser criterion 81
 - Shockley-Queisser limit 26, 99, 149, 151, 153
 - short range order 66
 - shunt 16-17, 24, 28-29, 180, 215, 229, 231, 234, 256, 266, 282, 298
 - Si SiO₂ interface 49
 - Si-F bond 69
 - Si-H alloy 236
 - Si-H bond 69
 - Siemens Process 31-34, 41, 62-63
 - silicone adhesive 207, 273
 - silicone gel 258, 318
 - silver selenide 6
 - simulation tools 345, 359, 385-386, 390, 394-395
 - single crystal Ge 35, 193
 - single crystal wafers 34
 - singlet fission 148-149
 - sintering 78, 94, 175-176, 186-187, 198
 - SiO₂ buffer layer 237
 - sizing of a SPV system 335
 - snail
 - track 6, 118, 265, 282, 329, 385
 - walk marks 265, 266
 - solar cell testing 277
 - solar cells
 - bulk crystalline 14, 92
 - CZTSSe 80-82, 92
 - dye-sensitized 46, 84, 125-126, 159
 - Multi Junction (MJ) 160, 192
 - nanowire/quantum dot-based 159
 - organic 83-84, 87-88, 95, 134-143, 145-153, 155-157, 159-160, 175, 200, 297, 304
 - Perovskite 83-93, 95-96
 - Photo-Electrochemical (PEC) 121
 - plasmonic 57-60, 65
 - space-quality 10, 120, 129

- tandem 27, 30, 35, 61, 65, 68, 71-74, 84-85, 88, 90-92, 96, 100, 103-104, 106, 109-116, 118, 129-130, 132-133, 144-145, 149-150, 157, 159, 203, 236-239, 243, 255, 257, 320
 thin film 13-14, 27, 30, 53, 57, 64, 66-67, 71-73, 75-81, 83-85, 87, 89, 91-95, 97-98, 100, 127, 130-131, 136, 144, 153, 158-160, 172, 174, 194, 198-199, 203-204, 219-222, 237-244, 255, 257, 295, 320-322, 325, 334-335, 352-353
 triple junction 106, 112, 192-193
 solar side meter 384
 solar simulator
 bottom loading type 283
 top loading type 283
 tunnel-type 284
 solderability of the metal 174
 solid angle 25, 323
 space-based solar power 120
 spatial non-uniformity 278-279
 spectral splitting 106-107, 114
 spectrum of light 221, 223
 spin coating 82, 86, 134, 148, 155
 spot soldering 211, 258
 spray pyrolysis 82
 spray technique 168
 sputtering 66, 68, 75-76, 78, 82, 97, 131, 242-243, 255
 SPV plant 244-246, 253, 335, 351-352, 358, 372, 383, 387, 392-393, 396, 398
 Staebler-Wronski effect 71, 72
 Standard Test Conditions (STC) 45
 stannite 80-81, 95
 statistical analyses 289
 statistical distribution functions 290
 steady-state simulator 280
 steel ball test 307
 stoichiometry 28, 75, 88, 224
 storage 3, 5-6, 122, 127-130, 133, 193, 307, 320, 322, 329-330, 335-337, 339-340, 345, 349, 353, 358-359, 366, 371-373, 375, 377, 379, 392, 395-396, 400
 strain in crystal
 strained layer 103
 street light 342-343
 string and array design 353, 358
 string design 259, 310-311, 330, 332-334, 354-355, 359
 subsidy 346, 356, 393-394
 substrate temperature 68, 72
 substrates
 flexible 66, 76, 94, 98, 131, 159
 plastic 73, 104, 135, 144-145, 156
 sulfation 373
 sun simulator 181, 259, 278-280, 283-284, 286, 313
 sun spectrum 278
 supercapacitor 371
 superstrate 159, 198, 203, 236, 255, 310
 supply chain management 243, 248
 surface modification 125
 surface orientation 48
 surface oxide 31
 surface plasma frequency 58
 surface plasmons 57-58, 145
 Surface Recombination Velocity (SRV) 49
 surface states 19, 49, 164-165, 183, 189
- T**
- tab pull strength 261-263
 Tabbing and Stringing (T&S) 188, 204, 260
 tabbing ribbon 212-215, 218, 256
 tandem
 cells 6-7, 9-11, 13-14, 16, 18-22, 25, 27-31, 33, 35, 37, 39, 41-43, 45-47, 49, 51, 53-61, 63-68, 70-81, 83-101, 103-163, 165, 167, 169, 171-183, 185-189, 191-206, 208-220, 222, 224-225, 227-229, 231, 233-237, 239-241, 243-244, 247, 250-252, 254-258, 260-269, 271, 273, 275, 280, 284-286, 296, 300, 304, 308, 310, 313-314, 319-320, 322, 333-335, 352, 377, 380, 382, 389
 mechanically stacked 90-92
 monolithically integrated 90-91
 spectrally split 90
 Tauc gap 68
 Tauc law 67
 TCO-coated glass 238
 tedler 205, 334
 Tejometer 5
 TEM 88
 temperature coefficients 45, 280, 326
 temperature cycle (TC) 297
 temperature de-rating 336, 379
 temperature de-rating factor (TDR) 379
 temperature gradient 6, 37-38
 temperature sensitivity 192, 372
 temporal stability 278-279
 terrestrial applications 104, 117, 160, 192, 197, 204, 333, 352
 test bench 180
 test chuck 181
 test till failure 309

412 • Index

testing of SPV modules 259
 tetragonal structure 84
 textured cover glass 211
 texturing the inner surface 220
 texturization 65, 162-163, 165-167, 187, 198-199, 285
 thermal conductivity 108
 thermal fluctuations 35
 thermal imaging cameras 56
 thermionic emission mechanism 23
 thermocouple 34, 269, 279, 315
 thermodynamic stability 129
 thermoelectric 6
 thermo-photonic 154
 thermophotovoltaic 6
 thick film effects 221
 thin film effects 219-221
 thin film technology 78, 158, 203, 237, 320-321, 335
 third generation photovoltaics 153, 157
 three bus bar cell 217
 tidal 3
 tilting of solar panel 5
 time-of-flight secondary ion mass spectrometry 89
 TiO₂ 30, 85-88, 90, 95, 113, 121, 124-127, 129, 141, 147
 TiO₂ nanoparticles 86, 126
 topaz solar farm 78
 total cost over lifetime 392, 394-395
 total energy produced 392-395
 toughened (tempered) glass 205
 toxicity 78-79, 92, 159
 tracking
 double-axis 5, 104
 manual 181, 262, 264, 267, 321
 single-axis 320-321, 324-325, 335, 352
 tracking structures 358
 transformer 329, 358, 368-369, 388, 393, 395
 transmission coefficient 20
 transmissivity 106
 transparent conductive coating 203
 Transparent Conductive Oxide (TCO) 237
 trap density 50
 trapped charge 50
 traps 71, 143, 241
 Trichloroethane (TCE) 190
 tri-layer stack up 221
 trimming process 206
 triple junction high efficiency cell 192
 tunnel junction 70, 111-113, 118, 145
 turnover 243

TUV 295
 twin boundaries 40

U

two-step sequential deposition 86
 ultra-violet photoemission spectroscopy (UPS) 90
 Underwriters Laboratories (UL) 295
 Upgraded Metallurgical-Grade (UMG) silicon 41
 urbach edge 67
 useful life 276, 288, 290, 293
 utility bills 253
 utilization factors 366
 UV chamber 297
 UV preconditioning test 297

V

valence band 8, 12, 22, 67, 78, 84, 90, 123, 129, 135, 147, 153, 263
 vanguard satellite 7
 vapour transport process 79
 vapour pressure 31, 88, 102
 Vapour-Assisted Solution Processing (VASP) 86, 88
 Variable Frequency Drive (VFD) 340
 vias 188
 violet cell 64
 visible spectrum 134, 152, 326
 visual inspection criteria 260
 Visual Tests 260
 Very Large Scale Integration (VLSI) 160
 voltage
 built-in 9, 14, 17, 23, 28-29, 70, 130, 161
 open circuit 9, 29, 59, 74, 109, 232, 234, 236, 256, 277, 279, 326

W

warranty 288, 352, 393
 water vapour 28, 135, 142, 300, 304
 wear out 288, 304-305
 weighted average 366
 wet leakage test 268-269
 window layer 27, 71, 76, 79, 82, 92, 99, 110, 112-114, 118, 241
 work function 18-19, 142, 144, 156
 world energy supply 2-3
 xenon arc lamp 278-279
 yellowing of EVA 296-297

Z

zone refining 31